DLAP-411-Orin Supreme

Compact Edge AI Platform for GenAI (LLM/VLM/ViTs) Applications

Features

- Affordable: Integrate Phison's aiDAPTIV+ AI technology to bypass edge memory up to 320GB, offloading expensive HBM and GDDR memory to cost-effective flash memory
- Elevated AI power: 8x faster TTFT and 4x longer token
- Provide 4 Eth and 4 USB 3.2 Gen 2
- Fanless and compact design: 175(W) x 145(D) x 85(H) mm
- Support Linux® Ubuntu 22.04 and Jetpack 6.2
- High efficiency Edge AI platform for on-premise GenAI deployments



Ordering Information

PN	Model Name	NVIDIA Module	NVIDIA Module Memory	NVIDIA Module eMMC	iDAPTIV+
93-45108-1110	DLAP-411-Orin Supreme	Jetson AGX Orin	32GB	64GB (pre-installed)	160GB
93-45108-3110	DLAP-411-Orin 64GB Supreme	Jetson AGX Orin	64GB	64GB (pre-installed)	320GB

Packing List*

PN	Description	QTY
93-45108-XX10	DLAP-411-Orin	1
33-70003-2000	Standoff A,M3,H5,Ni	2
46-20301-0000-A0	Screw M3,I-head,L4	3
47-90004-0010	Technical service card	1
50-40375-9000	Template A of both CN & TW RoHS Declarat	1

* Power adapter not included. Please order separately if needed.

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Optional Accessories

PN	Description	Note
29-E8852-A000	Wifi module, M2-R8852BE	Wi-Fi module only. Order 2 antennas (30-60125-1000-B0) if needed
29-D3096-K030	5G module, MV31-W	5G module only. Order 4 antennas (30-60192-0000-A0) if needed
29-D0520-G000	5G module, Quectel RM520N-GL	5G module only. Order 4 antennas (30-60192-0000-A0) if needed
29-D0034-8010	4G/LET module, Sierra EM7565	4G/LTE module only. Order 2 antennas (30-60192-0000-A0) if needed
30-60125-1000-B0	Antenna, WIFI Dual band Antenna 6E	Order in sets of 2
30-60192-0000-A0	Antenna, RP-SMA(M), 5G NR Sub-6	Order in sets of 2 or 4
31-62120-0020	Power adapter, GST160A24-AD	For non-PSE SKU, order this power adapter
31-62149-0000	Power adapter, GST220A24-AD	For PSE SKU, order this power adapter
91-95221-0010	Wall mounting Kit	

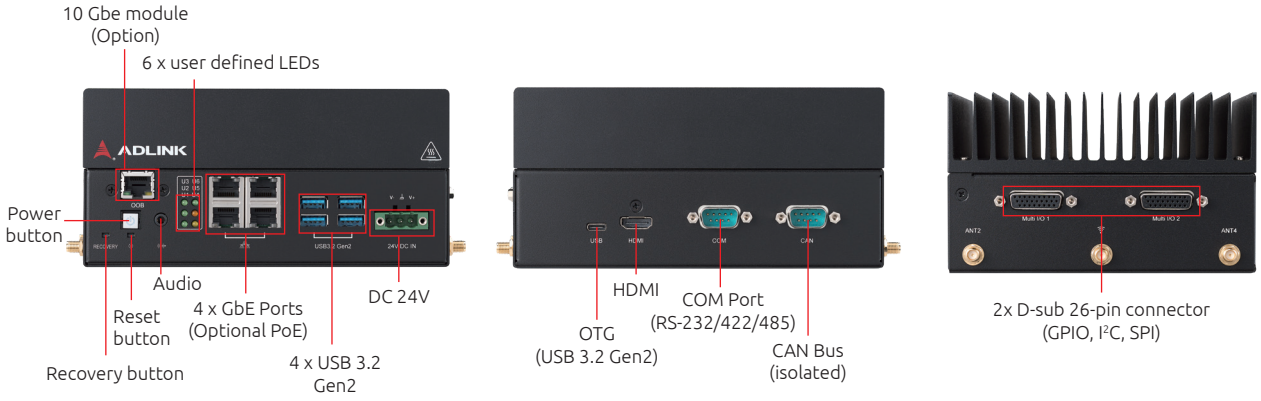
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Specifications

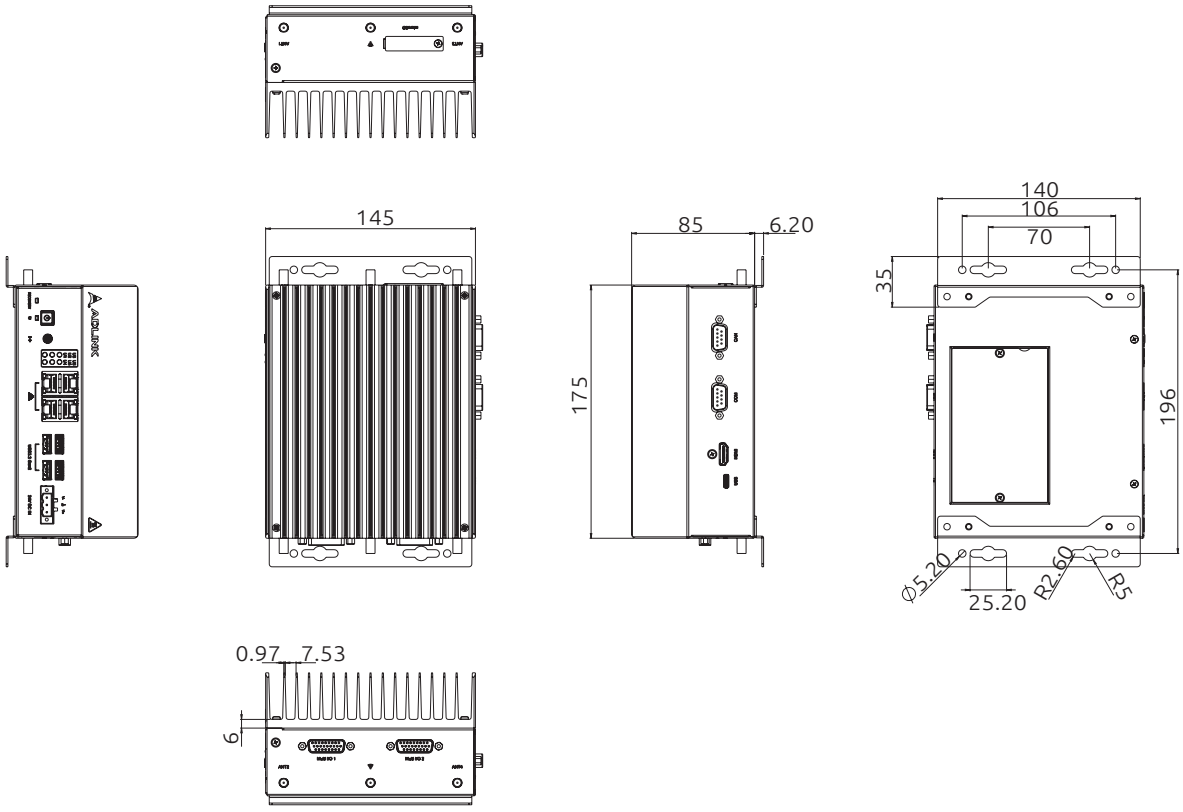
Model		DLAP-411-Orin Supreme	
AI Performance		200 TOPS	275 TOPS
System	GPU	NVIDIA Ampere architecture with 1792 NVIDIA® CUDA® cores and 56 Tensor Cores	NVIDIA Ampere architecture with 2048 NVIDIA® CUDA® cores and 64 Tensor Cores
	CPU	8-core Arm® Cortex®-A78AE v8.2 64-bit CPU 2MB L2 + 4MB L	12-core Arm® Cortex®-A78AE v8.2 64-bit CPU 3MB L2 + 6MB L3
	aiDAPTIV+	Phison AI100E M.2 SSD	
	RAM	32GB 256-bit LPDDR5	64GB 256-bit LPDDR5
	Storage	64GB eMMC 5.1	
	OS	Linux® Ubuntu	
Front I/O Interfaces	Button	1x power, 1x reset, 1x recovery	
	HDMI	1x HDMI (Max. resolution 3840x2160 @ 60Hz)	
	USB	4x USB 3.2 Gen2 Type-A	
	Ethernet	4x 10/100/1000Mbps Ethernets (Optional PoE support, IEEE 802.3af/at)	
	Audio	Mic-in (Mono), Line-out (Stereo)	
	I/O Connector	2x D-sub 26-pin connector (GPIO, I2C, SPI) provide cable for expansion	
Back I/O Interfaces	USB	1x USB 3.2 Gen2 Type-C (OTG)	
	Serial Port	1x COM RS-232/RS-422/RS-485 (DB9)	
	CAN Bus	1x 2.0b, isolated (DB9)	
Expansion Slots	M.2	M.2 for SSD	
	SD Card	1x MicroSD Slot	
	Out-Of-Band (OOB)	Support Ethernet and Wifi, monitoring and managing at remote locations (thermal sensor, remote power on/off, restart, monitor debug port detection device status.)	
LED indicator		6x user defined LEDs	
Power Supply	DC Input	24V	
	AC Input	160 up to 220W power adapter	
	Power switch	1x Power ON/OFF Button (AT/ATX , Default : AT)	
Mechanical	Dimensions (W x D x H)	175x 145x 85mm	
	Weight	2.2 kg	
	Mounting	Wall mount, VESA DIN rail (optional)	
	SMA Antenna Connector	6	
Environmental	Operating Temperature	For 32GB -20°C to 60°C with 0.6m/s airflow, at 40W (without wifi module, M.2 SSD) -20°C to 55°C with 0.6m/s airflow, at MAXN (without wifi module, M.2 SSD) For 64GB -20°C to 55°C with 0.6m/s airflow, at 50W (without wifi module, M.2 SSD) -20°C to 40°C with 0.6m/s airflow, at MAXN (without wifi module, M.2 SSD)	
	Operating Humidity	~95% @40°C (non-condensing, optional with fanless solution)	
	Storage Temperature	-40°C to 85°C	
	Vibration	Operating 5Grms, 5-500Hz, 3 axes w/M.2 SSD	
	Shock	Operating 100G, half sine 11ms duration w/ SD, M.2 SSD	
	ESD	Contact ± 4kV, Air ± 8kV	
	Regularity	CE & FCC class B, (EN61000-6-4/-6-2), CE-LVD & UL by CB, FCCID	
Internal	Thermal sensor	1x Thermal sensor	
F/W Support	WDT	WDT supported	

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I/O View



Product Dimensions and Illustration



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